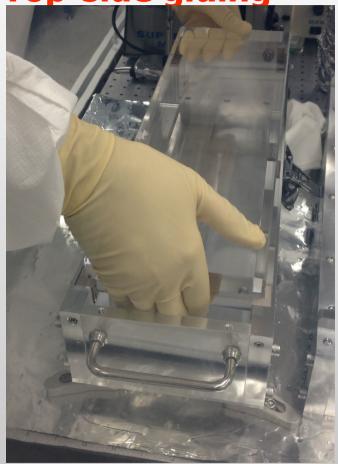
OMC building status

- Glass components on the OMC top side (non-optic side) were glued: with gluing template. The process went well.
- PZT assembly:
 - PZT-glass joints by UV epoxy showed reduction of the "wet" area by \sim 30%.
 - => After repeated finger poking, the PZT-Prism joint was detached. (though it was not easy)
 - We are preparing to switch the glue to EP30-2 for the PZT-glass joints
- DCPD/QPD mount, cable harness: In the baking oven. Will come back shortly
- Black glass beam damps: Arrived from MIT. Inspected.
- Cavity locking optics: Beam coming out form a mode cleaning fiber.

 Locking will be tested by a "dummy" OMC
- 13 DCPD diodes (C30665GH): Tested. Q.E. with the glass window =~85% 9 selected => In the C&B process

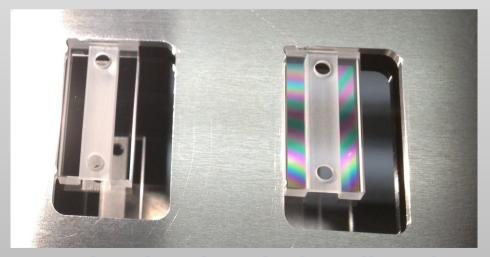
Top-side gluing



Placing the glass breadboard in the transporting (building) fixture

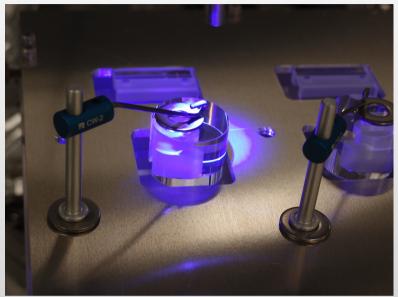
v top-gluing template





^ optics placed on the breadboard (no UV epoxy applied yet)

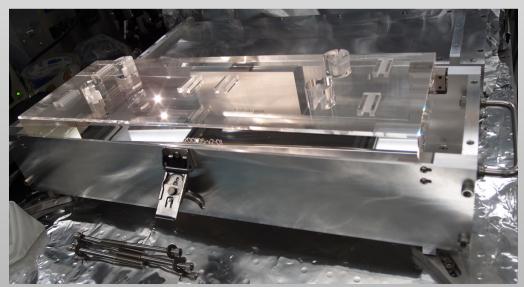
Top-side gluing 2

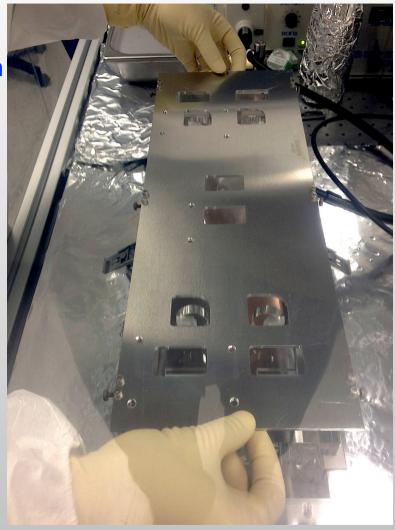


UV illuminaiton

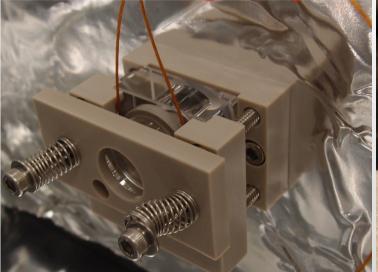
Removing template ->

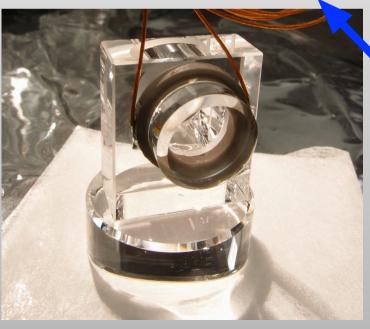
v Top side completed!

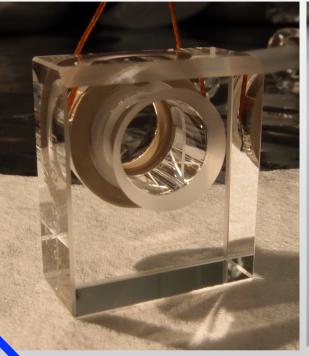




PZT-Prism gluing







Before the bake ^



^ After the heat process for epoxy cure (100degC ~1 hour)

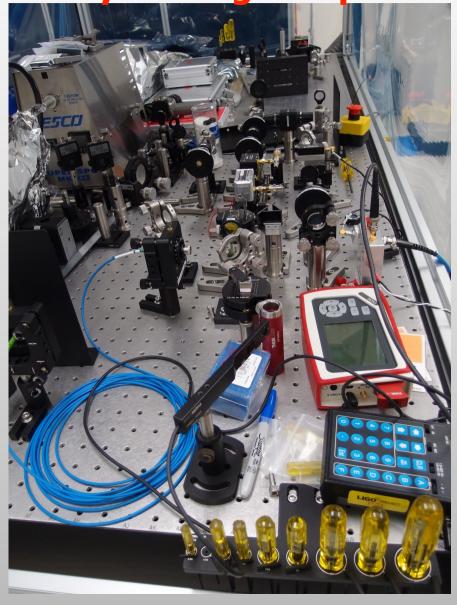
Gluing fixture

<glued PZT assembly

Beam dump



Cavity locking setup



PD #11

Measurement Date:

Mar. 17, 2013

Imepedance measured at $V_R = 15V$

Shunt Resistance (R_{SH}):

Elem1: 13.905 MOhm

Series Resistance: (R_s):

Elem1: 10.0 Ohm

Junction Capacitance: (C_{pd}):

Elem1: 212.9 pF

Dark Current [nA]:

Elem1: 3.48 nA

Dark Noise: 1~10Hz avg

Elem1: 0.674 pA/rtHz

200~290Hz avg

Elem1: 0.128 pA/rtHz

Total Penalty: -5

